

### Features

- High current capability
- Avalanche rated
- Low forward voltage drop
- High frequency operation

### Description

The STPS30SM60D is a single diode Schottky rectifier, suited for high frequency switch mode power supply.

Packaged in TO-220AC, this device is intended to be used in notebook, game station and desktop adapters, providing in these applications a good efficiency at both low and high load.

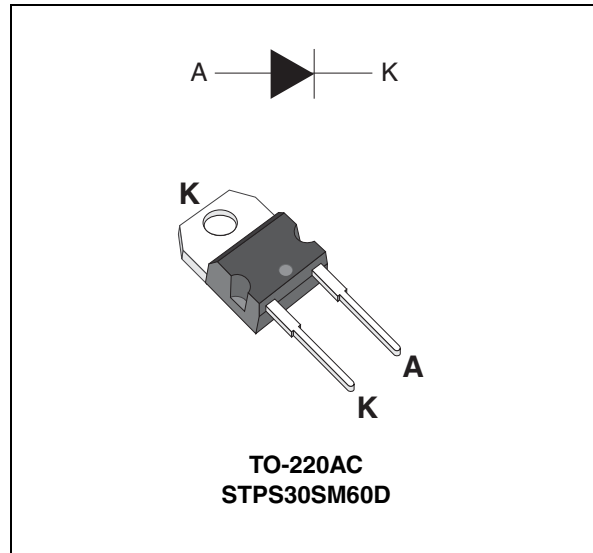
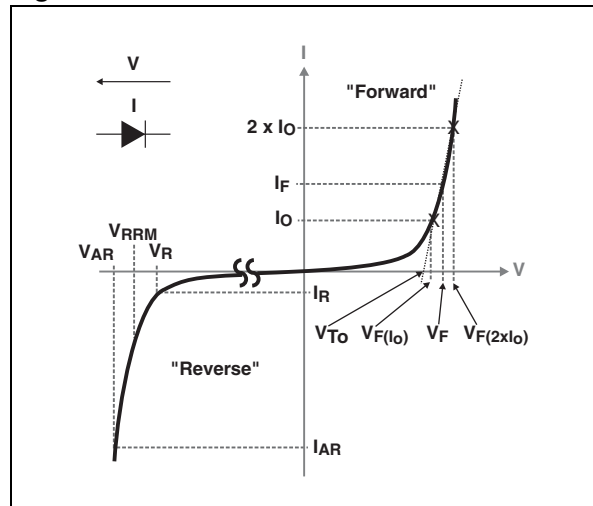


Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	30 A
$V_{RRM}$	60 V
$V_F$ (typ)	0.410 V
$T_j$ (max)	150 °C

Figure 1. Electrical characteristics(a)



- a.  $V_{ARM}$  and  $I_{ARM}$  must respect the reverse safe operating area defined in [Figure 11](#).  $V_{AR}$  and  $I_{AR}$  are pulse measurements ( $t_p < 1 \mu s$ ).  $V_R$ ,  $I_R$ ,  $V_{RRM}$  and  $V_F$  are static characteristics

# 1 Characteristics

**Table 2. Absolute ratings (limiting values, at  $T_{amb} = 25\text{ °C}$  unless otherwise specified)**

Symbol	Parameter	Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage	60	V
$I_{F(RMS)}$	Forward rms current	60	A
$I_{F(AV)}$	Average forward current, $\delta = 0.5$	$T_c = 125\text{ °C}$	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms}$ sine-wave	A
$P_{ARM}^{(1)}$	Repetitive peak avalanche power	$T_j = 25\text{ °C}$ , $t_p = 1\text{ }\mu\text{s}$	W
$V_{ARM}^{(2)}$	Maximum repetitive peak avalanche voltage	$t_p < 1\text{ }\mu\text{s}$ , $T_j < 150\text{ °C}$ , $I_{AR} < 105\text{ A}$	V
$V_{ASM}^{(2)}$	Maximum repetitive peak avalanche voltage	$t_p < 1\text{ }\mu\text{s}$ , $T_j < 150\text{ °C}$ , $I_{AR} < 105\text{ A}$	V
$T_{stg}$	Storage temperature range	-65 to +175	°C
$T_j$	Maximum operating junction temperature <sup>(3)</sup>	150	°C

1. For temperature or pulse time duration deratings, please refer to [Figure 4](#) and [5](#). More details regarding the avalanche energy measurements and diode validation in the avalanche are provided in the application notes AN1768 and AN2025.

2. See [Figure 11](#)

3.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal parameters**

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	1.0	°C/W

**Table 4. Static electrical characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	-	30	135	$\mu\text{A}$
		$T_j = 125\text{ °C}$	-	20	80	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	-	0.500	0.540	V
		$T_j = 125\text{ °C}$	-	0.410	0.470	
		$T_j = 25\text{ °C}$	-	0.570	0.640	
		$T_j = 125\text{ °C}$	-	0.515	0.600	

1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.435 \times I_{F(AV)} + 0.0055 \times I_{F(RMS)}^2$$

Figure 2. Average forward power dissipation versus average forward current

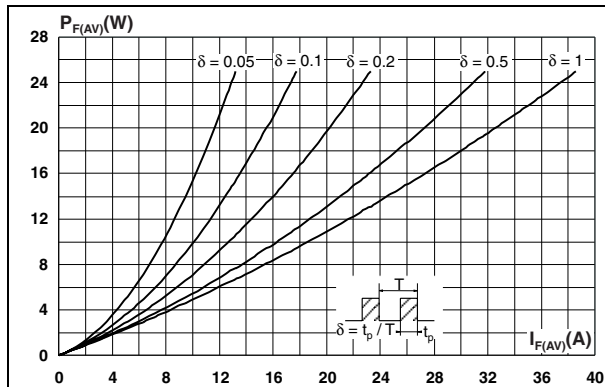
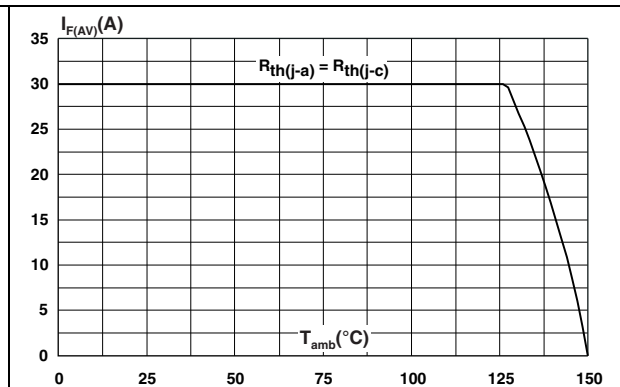
Figure 3. Average forward current versus ambient temperature ( $\delta = 0.5$ )

Figure 4. Normalized avalanche power derating versus pulse duration

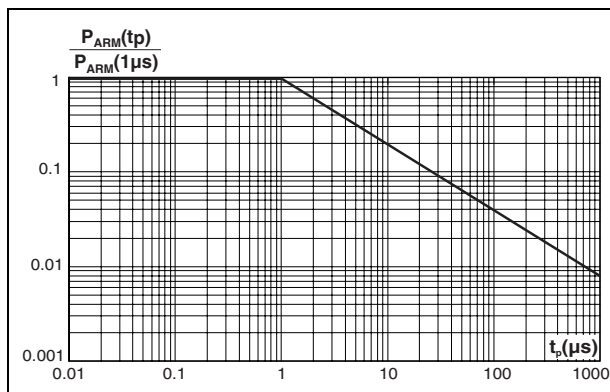


Figure 5. Normalized avalanche power derating versus junction temperature

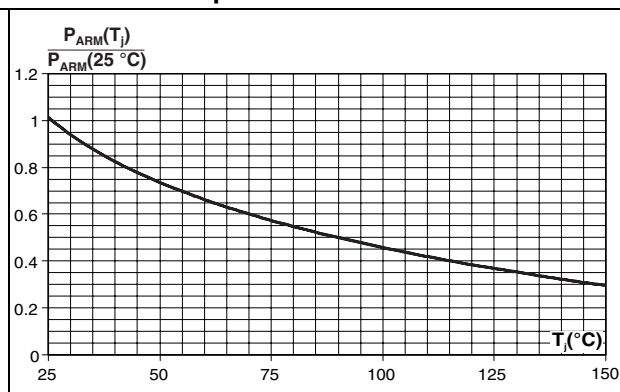


Figure 6. Non repetitive surge peak forward current versus overload duration (maximum values)

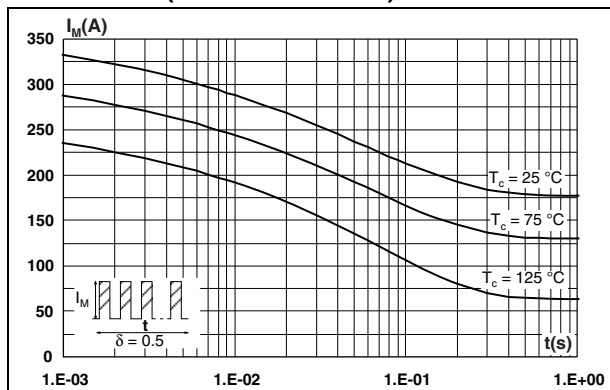
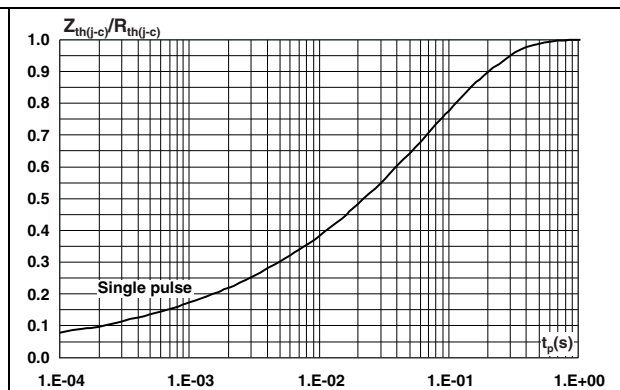
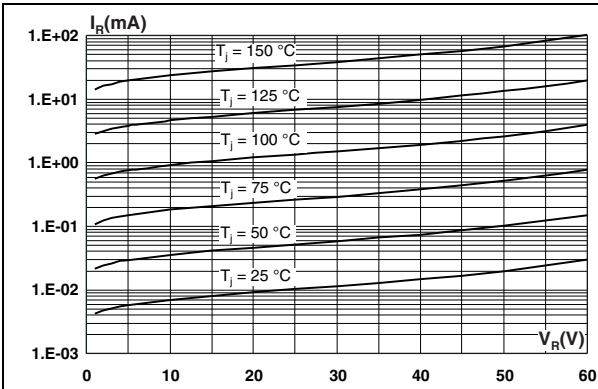


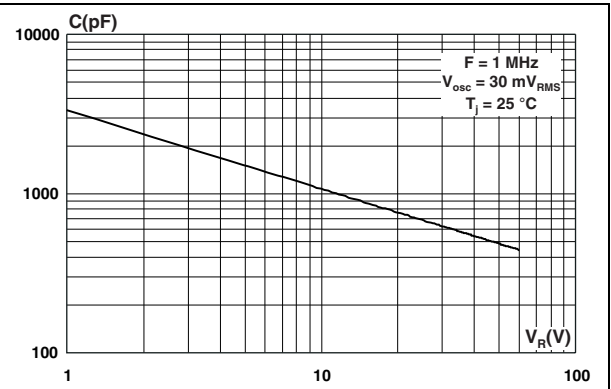
Figure 7. Relative thermal impedance junction to case versus pulse duration



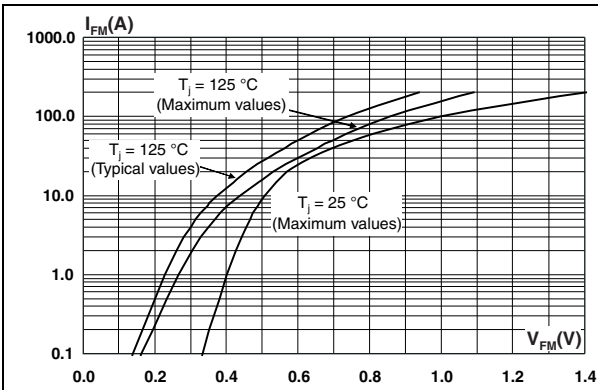
**Figure 8. Reverse leakage current versus reverse voltage applied (typical values)**



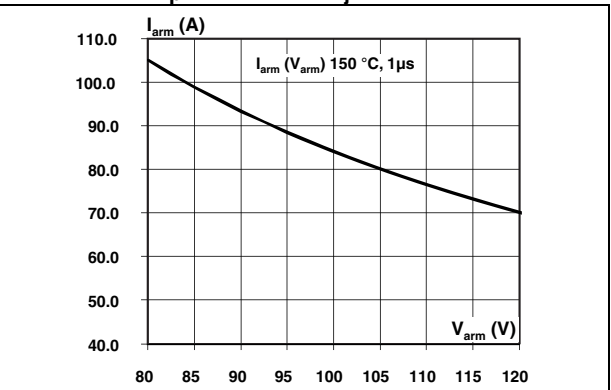
**Figure 9. Junction capacitance versus reverse voltage applied (typical values)**



**Figure 10. Forward voltage drop versus forward current**



**Figure 11. Reverse safe operating area ( $t_p < 1 \mu s$  and  $T_J < 150 \text{ }^\circ\text{C}$ )**



## 2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.4 to 0.6 N·m

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**Table 5. TO-220AC dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

### 3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS30SM60D	STPS30SM60D	TO-220AC	1.86 g	50	Tube

### 4 Revision history

Table 7. Revision history

Date	Revision	Changes
14-Oct-2011	1	Initial release.

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